



(12) **Patent Application Publication**
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(43) **Pub. Date:** **May 30, 2024**

H05K 3/18 (2006.01)

(52) **U.S. Cl.**
CPC ***H05K 1/0224*** (2013.01); ***H05K 1/115***
(2013.01); ***H05K 3/107*** (2013.01); ***H05K***
3/188 (2013.01); ***H05K 2201/09036*** (2013.01);
H05K 2201/096 (2013.01)

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(57) **ABSTRACT**

The present disclosure relates to a printed circuit board. The printed circuit board includes a plurality of insulating layers each having a plurality of concave portions; a plurality of conductor pattern layers disposed in a plurality of concave portions of each of the plurality of insulating layers; first and second via holes connected to one of the plurality of concave portions independently of each other and penetrating through at least two of the plurality of insulating layers independently of each other; and first and second via conductors disposed in the first and second via holes, respectively, and connecting two of the plurality of conductor pattern layers independently of each other. An average width of the first via conductor is greater than that of the second via conductor on a cross-section.

(22) Filed: **Feb. 6, 2023**

(30) **Foreign Application Priority Data**

Nov. 29, 2022 (KR) 10-2022-0163065

Publication Classification

(51) **Int. Cl.**
H05K 1/02 (2006.01)
H05K 1/11 (2006.01)

